

# HIGH-SPEED, SINGLE-SUPPLY, RAIL-TO-RAIL OPERATIONAL AMPLIFIER MicroAmplifier™ SERIES

Check for Samples: [OPA4350-DIE](#)

## FEATURES

- Rail-to-Rail Input
- Rail-to-Rail Output
- Wide Bandwidth
- High Slew Rate
- Low Noise
- Low THD+Noise
- Unity-Gain Stable

## APPLICATIONS

- Cell Phone PA Control Loops
- Driving A/D Converters
- Video Processing
- Data Acquisition
- Process Control
- Audio Processing
- Communications
- Active Filters
- Test Equipment

## DESCRIPTION

The OPA4350 rail-to-rail CMOS operational amplifier is optimized for low voltage, single-supply operation. Rail-to-rail input/output, low noise, and high speed operation makes it ideal for driving sampling analog-to-digital (A/D) converters. It is also well suited for cell phone PA control loops and video processing (75-Ω drive capability) as well as audio and general purpose applications.

The OPA4350 operates on a single supply as low as 2.5 V with an input common-mode voltage range that extends 300 mV below ground and 300 mV above the positive supply.

## ORDERING INFORMATION<sup>(1)</sup>

| PRODUCT | PACKAGE DESIGNATOR | PACKAGE                                | ORDERABLE PART NUMBER | PACKAGE QUANTITY |
|---------|--------------------|----------------------------------------|-----------------------|------------------|
| OPA4350 | TD                 | Bare Die In Waffle Pack <sup>(2)</sup> | OPA4350TDC1           | 130              |
|         |                    |                                        | OPA4350TDC2           | 10               |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

MicroAmplifier is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2012, Texas Instruments Incorporated

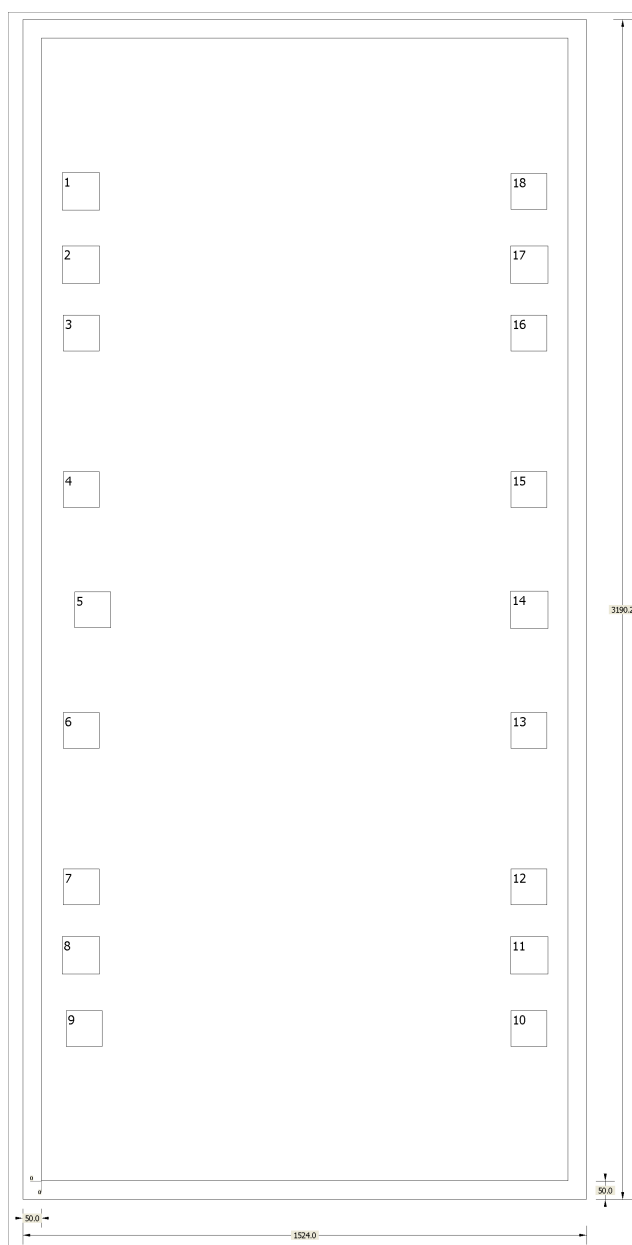


This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### BARE DIE INFORMATION

| DIE THICKNESS | BACKSIDE FINISH        | BACKSIDE POTENTIAL | BOND PAD METALLIZATION COMPOSITION | BOND PAD THICKNESS |
|---------------|------------------------|--------------------|------------------------------------|--------------------|
| 10.5 mils.    | Silicon with backgrind | Floating           | Ti/AlSiCu/TiN                      | 800 nm             |



**Table 1. Bond Pad Coordinates in Microns<sup>(1)</sup>**

| DESCRIPTION | PAD NUMBER | X MIN   | Y MIN   | X MAX   | Y MAX   |
|-------------|------------|---------|---------|---------|---------|
| Out A       | 1          | 5       | 2550.35 | 107     | 2652.35 |
| N/C         | 2          | 5       | 2352.5  | 107     | 2454.5  |
| -In A       | 3          | 7.65    | 2168.95 | 105.65  | 2266.95 |
| +In A       | 4          | 7.65    | 1746.1  | 105.65  | 1844.1  |
| V+          | 5          | 38.9    | 1420.7  | 136.9   | 1518.7  |
| +In B       | 6          | 7.65    | 1095.3  | 105.65  | 1193.3  |
| -In B       | 7          | 7.65    | 672.45  | 105.65  | 770.45  |
| N/C         | 8          | 5       | 484.9   | 107     | 586.9   |
| Out B       | 9          | 15.85   | 289.45  | 113.85  | 387.45  |
| Out C       | 10         | 1218.35 | 289.45  | 1316.35 | 387.45  |
| N/C         | 11         | 1217    | 484.9   | 1319    | 586.9   |
| -In C       | 12         | 1218.35 | 672.45  | 1316.35 | 770.45  |
| +In C       | 13         | 1218.35 | 1095.3  | 1316.35 | 1193.3  |
| V-          | 14         | 1217    | 1418.7  | 1319    | 1520.7  |
| +In D       | 15         | 1218.35 | 1746.1  | 1316.35 | 1844.1  |
| -In D       | 16         | 1218.35 | 2168.95 | 1316.35 | 2266.95 |
| N/C         | 17         | 1217    | 2352.5  | 1319    | 2454.5  |
| Out D       | 18         | 1218.35 | 2551.95 | 1316.35 | 2649.95 |

(1) Substrate floating

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/ Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|-------------------|------------------------------|--------------------------|
| OPA4350TDC1      | ACTIVE                |              |                 | 0    | 130         | TBD                     | Call TI           | N / A for Pkg Type           |                          |
| OPA4350TDC2      | ACTIVE                |              |                 | 0    | 10          | TBD                     | Call TI           | N / A for Pkg Type           |                          |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

|                        |                                                                                      |
|------------------------|--------------------------------------------------------------------------------------|
| Audio                  | <a href="http://www.ti.com/audio">www.ti.com/audio</a>                               |
| Amplifiers             | <a href="http://amplifier.ti.com">amplifier.ti.com</a>                               |
| Data Converters        | <a href="http://dataconverter.ti.com">dataconverter.ti.com</a>                       |
| DLP® Products          | <a href="http://www.dlp.com">www.dlp.com</a>                                         |
| DSP                    | <a href="http://dsp.ti.com">dsp.ti.com</a>                                           |
| Clocks and Timers      | <a href="http://www.ti.com/clocks">www.ti.com/clocks</a>                             |
| Interface              | <a href="http://interface.ti.com">interface.ti.com</a>                               |
| Logic                  | <a href="http://logic.ti.com">logic.ti.com</a>                                       |
| Power Mgmt             | <a href="http://power.ti.com">power.ti.com</a>                                       |
| Microcontrollers       | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a>                   |
| RFID                   | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
| OMAP Mobile Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
| Wireless Connectivity  | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

### Applications

|                               |                                                                                          |
|-------------------------------|------------------------------------------------------------------------------------------|
| Automotive and Transportation | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
| Medical                       | <a href="http://www.ti.com/medical">www.ti.com/medical</a>                               |
| Security                      | <a href="http://www.ti.com/security">www.ti.com/security</a>                             |
| Space, Avionics and Defense   | <a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a> |
| Video and Imaging             | <a href="http://www.ti.com/video">www.ti.com/video</a>                                   |

**TI E2E Community** [e2e.ti.com](http://e2e.ti.com)